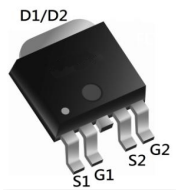
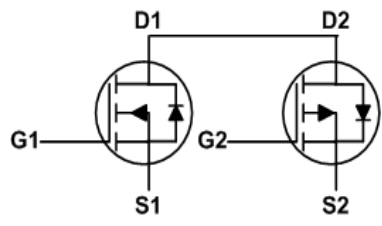


**60V N-Channel MOSFET
-60V P-Channel MOSFET**
●General Description

The N-ch and P-ch MOSFET LH4559A has the low RDS(on), low gate charge, fast switching and excellent avalanche characteristics. This device is suitable for fast charge and lighting.

●Features

- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density trench technology

 TO-252-4	VDS =60V RDS(ON)=30mΩ ID =7.0A
	VDS =-60V RDS(ON)=71mΩ ID =-6.0A
 ■ RoHS COMPLIANT	

●Ordering Information:

Part number	LH4559A
Package	TO252-4
Basic ordering unit (pcs)	2500
Normal Package Material Ordering Code	LH4559AT7-TO252-4-TAP
Halogen Free Ordering Code	LH4559AT7-TO252-4-TAP-HF

●Absolute Maximum Ratings (TC =25℃)

PARAMETER	SYMBOL	Value		UNIT
		N-ch	P-ch	
Drain-Source Breakdown Voltage	BV _{DSS}	60	-60	V
Gate-Source Voltage	V _{GS}	±20	±20	V
Continuous Drain Current	ID @TA=25℃	7.0	-6.0	A
	ID@TA=100℃	5.5	-4.5	
Pulsed drain current	IDM	11	-8.5	A
Avalanche Energy	E _{AS}	25.5	35.3	mJ
Avalanche Current	I _{AS}	22.6	-26.6	W
Power Dissipation @TA=25℃	P _D	1.5	1.5	
Operating Temperature	T _J	-55~+150	-55~+150	℃
Storage Temperature	T _{STG}	-55~+150	-55~+150	℃

60V N-Channel MOSFET
-60V P-Channel MOSFET
●N-Channel Electronic Characteristics

PARAMETER	SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNIT
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	60	--	--	V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	--	2.5	V
Drain-source On Resistance ²	$R_{DS(ON)}$	$V_{GS}=10V, I_D=4A$		30	35	mΩ
		$V_{GS}=4.5V, I_D=2A$	--	37	43	
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=48V, V_{GS}=0V, T_J=25^\circ C$	--	--	1	uA
		$V_{DS}=48V, V_{GS}=0V, T_J=55^\circ C$	--	--	5	
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	--	--	± 100	nA
Forward Transconductance	g_{fs}	$V_{DS}=5V, I_D=4A$	--	21	--	S
Input Capacitance	C_{iss}	$V_{GS}=0V, V_{DS}=15V, f=1.0MHz$	--	1378	--	pF
Output Capacitance	C_{oss}		--	86	--	
Reverse Transfer Capacitance	C_{rss}		--	64	--	ns
Gate Resistance	R_g	$V_{DS}=0V, V_{GS}=0V, f=1MHz$	--	3.2	---	Ω
Total Gate Charge (10V)	Q_g	$V_{DS}=48V, V_{GS}=4.5V, I_D=4A$	--	12.6	---	nC
Gate-Source Charge	Q_{gs}		--	3.2	--	
Gate-Drain Charge	Q_{gd}		--	6.3	--	
Turn-On Delay Time	$T_{d(on)}$	$V_{DD}=30V, V_{GS}=10V, R_G=3.3\Omega, I_D=14A$	--	8	--	nS
Rise Time	T_r		--	14.2	--	
Turn-Off Delay Time	$T_{d(off)}$		--	24.4	---	
Fall Time	T_f		--	4.6	7.0	
Continuous Source Current ^{1,5}	I_S	$V_G=V_D=0V, \text{Force Current}$	--	--	70	A
Pulsed Source Current ^{2,5}	I_{SD}		--	--	12	
Diode Forward Voltage ²	V_{SD}	$V_{GS}=0V, I_S=1A, T_J=25^\circ C$	--	--	1.2	V

Notes:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=22.6A$
4. The power dissipation is limited by $150^\circ C$ junction temperature
5. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

60V N-Channel MOSFET
-60V P-Channel MOSFET
●P-Channel Electronic Characteristics

PARAMETER	SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNIT
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=-250\mu A$	-60	--	--	V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS}=V_{DS}, I_D=-250\mu A$	-1.2	--	-2.5	V
Drain-source On Resistance ²	$R_{DS(ON)}$	$V_{GS}=-10V, I_D=4A$		71	87	mΩ
		$V_{GS}=-4.5V, I_D=2A$	--	90	120	
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=-48V, V_{GS}=0V, T_J=25^\circ C$	--	--	1	uA
		$V_{DS}=-48V, V_{GS}=0V, T_J=55^\circ C$	--	--	5	
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	--	--	± 100	nA
Forward Transconductance	g_{fs}	$V_{DS}=-5V, I_D=-3A$	--	15	--	S
Input Capacitance	C_{iss}	$V_{GS}=0V, V_{DS}=-15V, f=1.0MHz$	--	1447	--	pF
Output Capacitance	C_{oss}		--	97.3	--	
Reverse Transfer Capacitance	C_{rss}		--	70	--	ns
Gate Resistance	R_g	$V_{DS}=0V, V_{GS}=0V, f=1MHz$	--	13.5	---	Ω
Total Gate Charge (10V)	Q_g	$V_{DS}=-48V, V_{GS}=-4.5V, I_D=-3A$	--	9.86	---	nC
Gate-Source Charge	Q_{gs}		--	3.1	--	
Gate-Drain Charge	Q_{gd}		--	2.95	--	
Turn-On Delay Time	$T_{d(on)}$	$V_{DD}=-15V, V_{GS}=-10V, R_G=3.3\Omega, I_D=-1A$	--	28.8	--	nS
Rise Time	T_r		--	19.8	--	
Turn-Off Delay Time	$T_{d(off)}$		--	60.8	---	
Fall Time	T_f		--	7.2	7.0	
Continuous Source Current ^{1,5}	I_S	$V_G=V_D=0V, \text{Force Current}$	--	--	-6.0	A
Pulsed Source Current ^{2,5}	I_{SD}		--	--	-11	
Diode Forward Voltage ²	V_{SD}	$V_{GS}=0V, I_S=-1A, T_J=25^\circ C$	--	--	-1.2	V

Notes:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is $V_{DD}=-25V, V_{GS}=-10V, L=0.1mH, I_{AS}=-26.6A$
4. The power dissipation is limited by 150℃ junction temperature
5. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

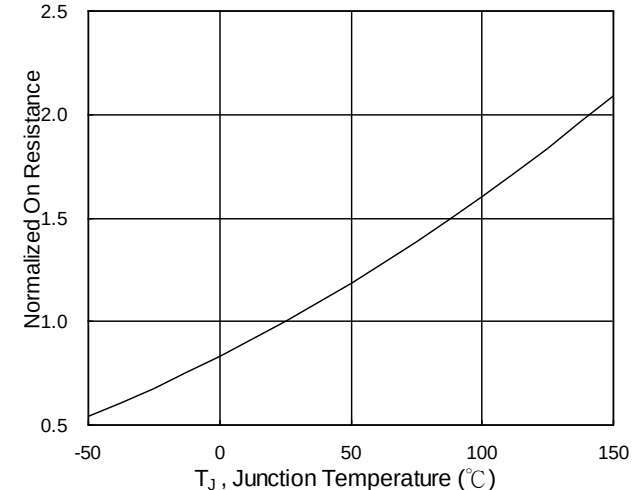
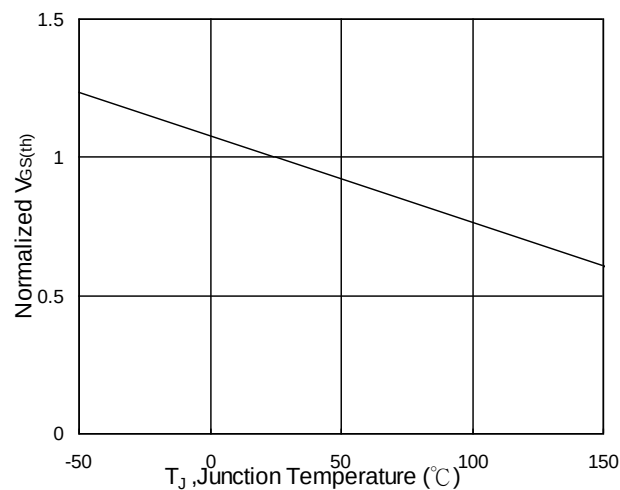
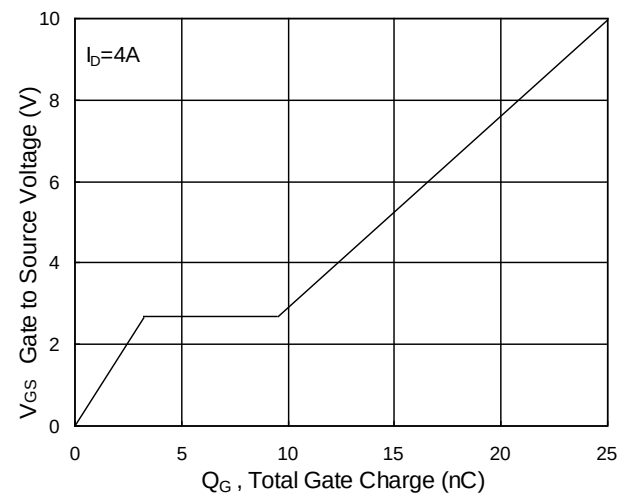
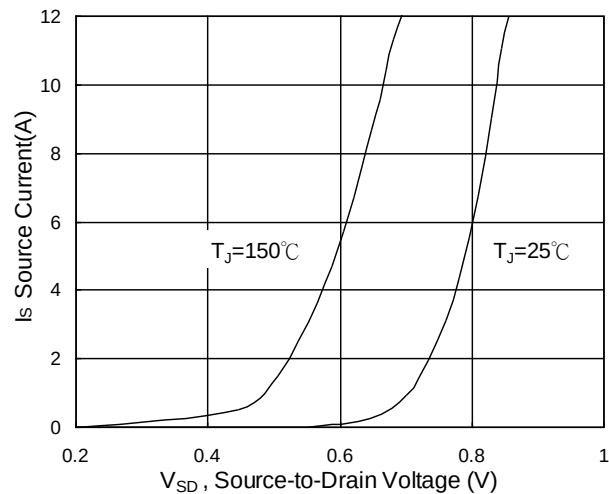
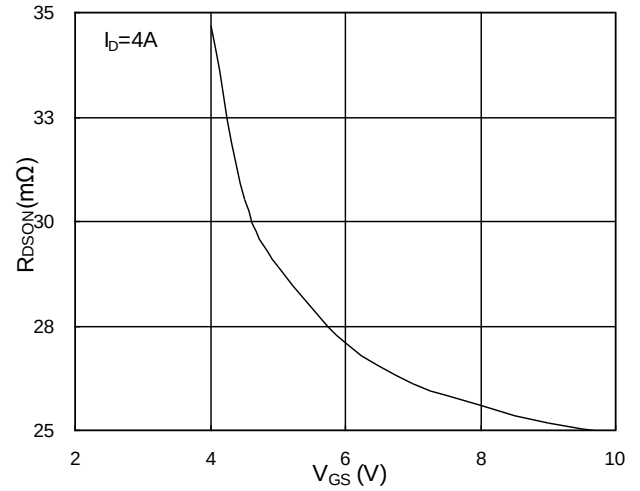
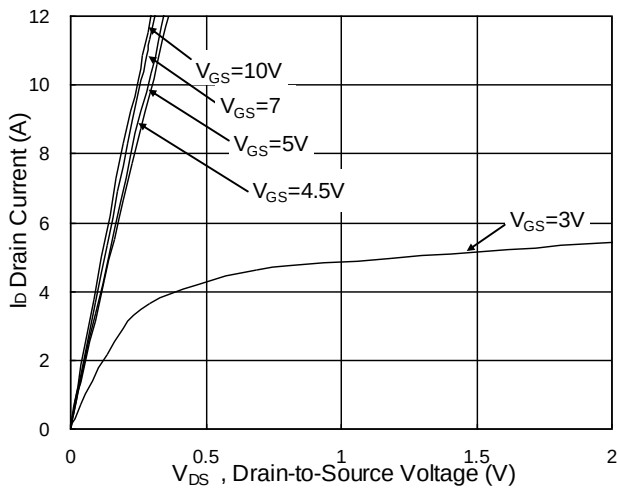
60V N-Channel MOSFET
-60V P-Channel MOSFET

●Thermal Characteristics

PARAMETER	SYMBOL	MAX	UNIT
		SOP-8	
Thermal Resistance Junction-case ¹	Rth _{JC}	36	°C/W
Thermal Resistance Junction-ambient ¹	Rth _{JA}	85	°C/W

**60V N-Channel MOSFET
-60V P-Channel MOSFET**

● **N-Channel Typical Characteristics**



60V N-Channel MOSFET
-60V P-Channel MOSFET

•N-Channel Typical Characteristics (cont.)

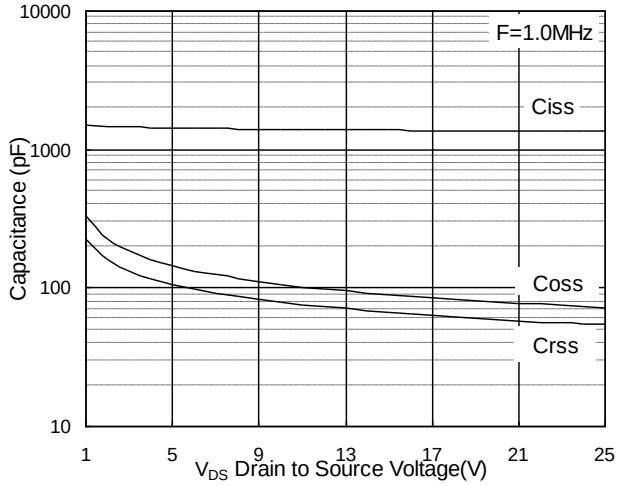


Fig.7 Capacitance

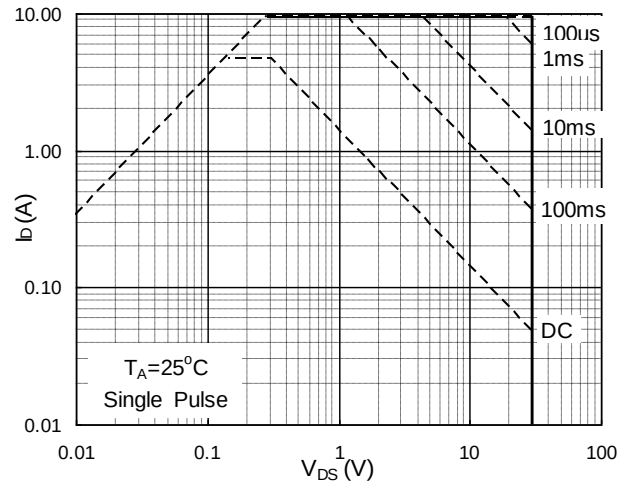


Fig.8 Safe Operating Area

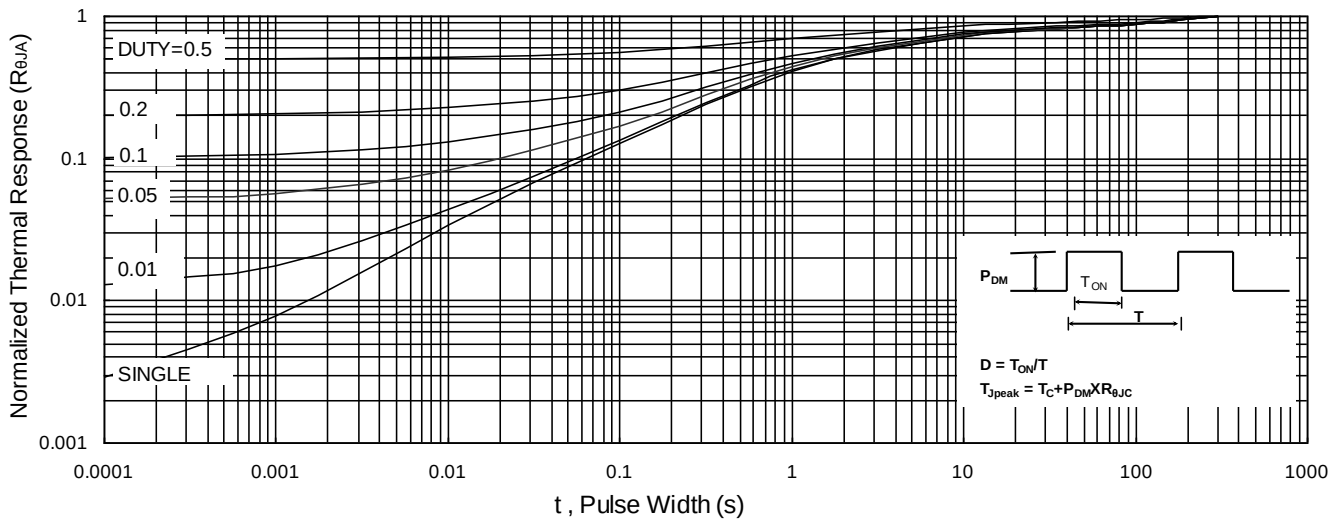


Fig.9 Normalized Maximum Transient Thermal Impedance

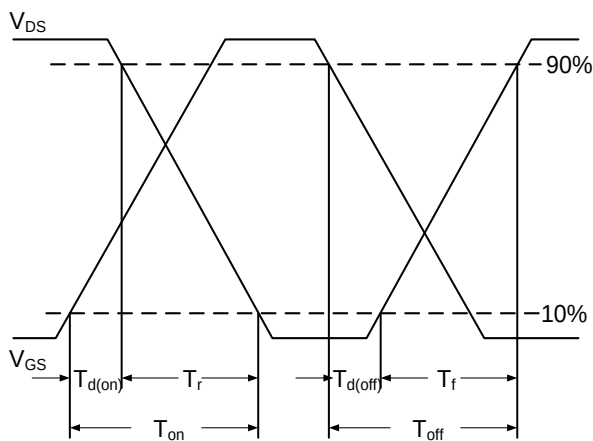


Fig.10 Switching Time Waveform

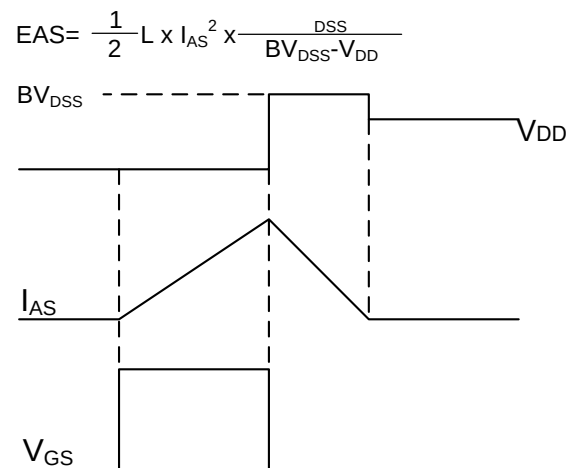


Fig.11 Unclamped Inductive Waveform

**60V N-Channel MOSFET
-60V P-Channel MOSFET**

• **P-Channel Typical Characteristics (cont.)**

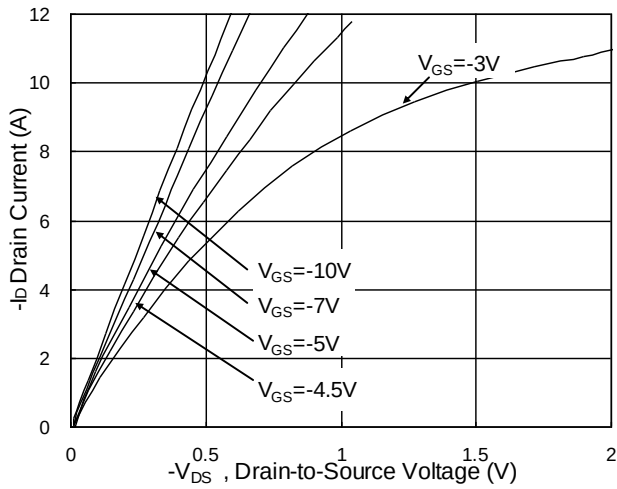


Fig.1 Typical Output Characteristics

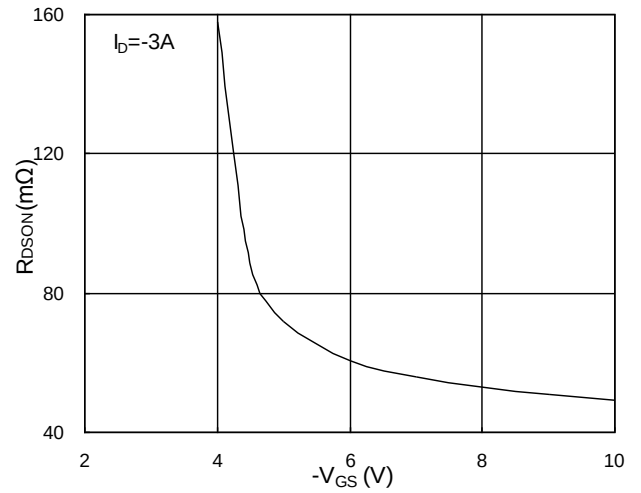


Fig.2 On-Resistance v.s Gate-Source

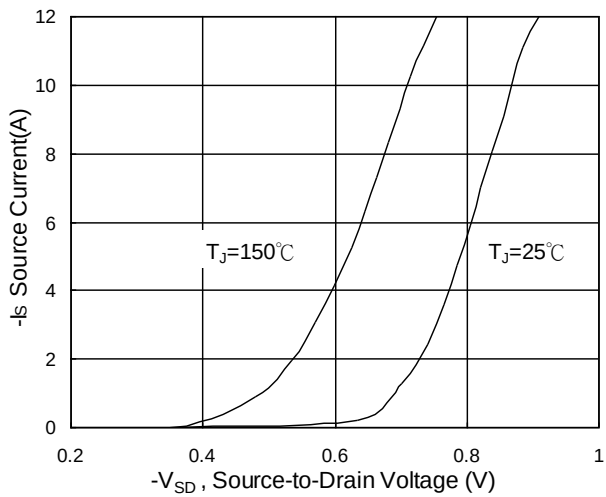


Fig.3 Forward Characteristics of Reverse

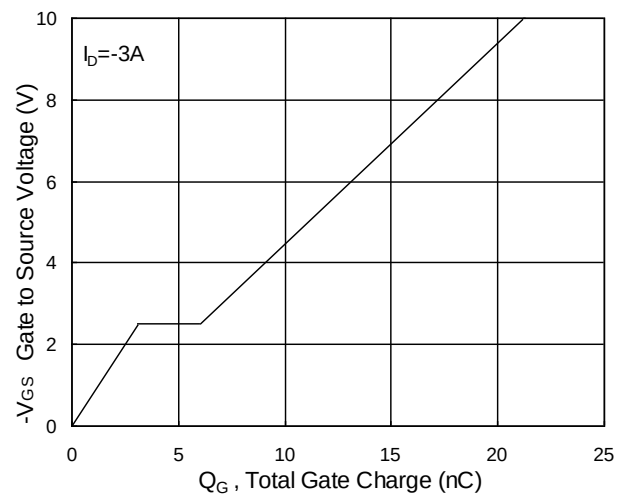


Fig.4 Gate-Charge Characteristics

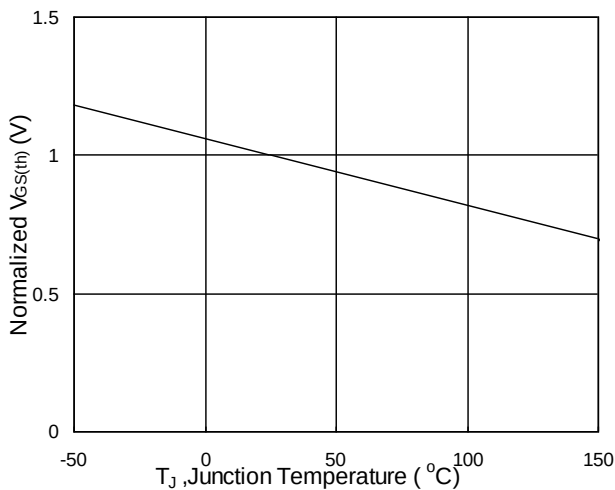


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

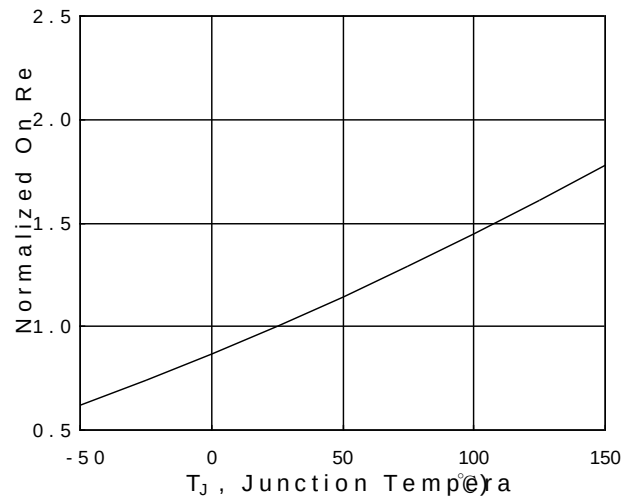


Fig.6 Normalized $R_{DS(on)}$ v.s T_J

**60V N-Channel MOSFET
-60V P-Channel MOSFET**

•P-ChannelTypical Characteristics (cont.)

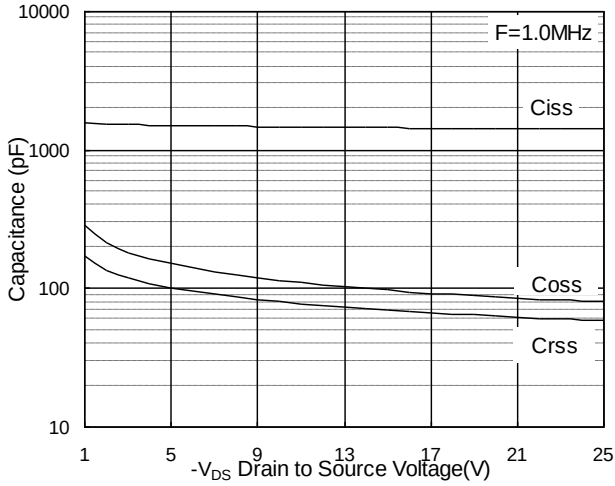


Fig.7 Capacitance

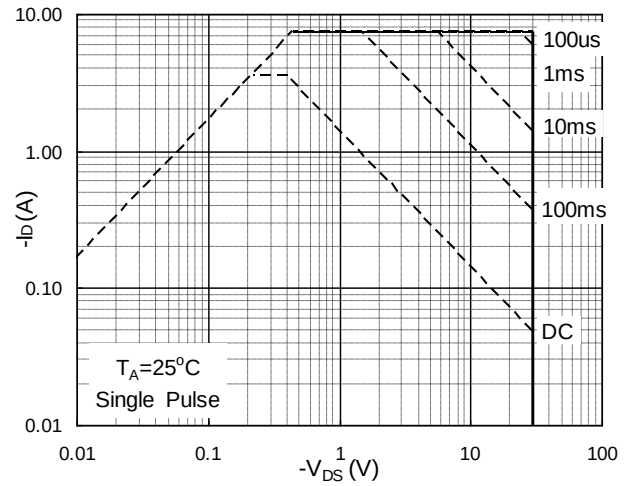


Fig.8 Safe Operating Area

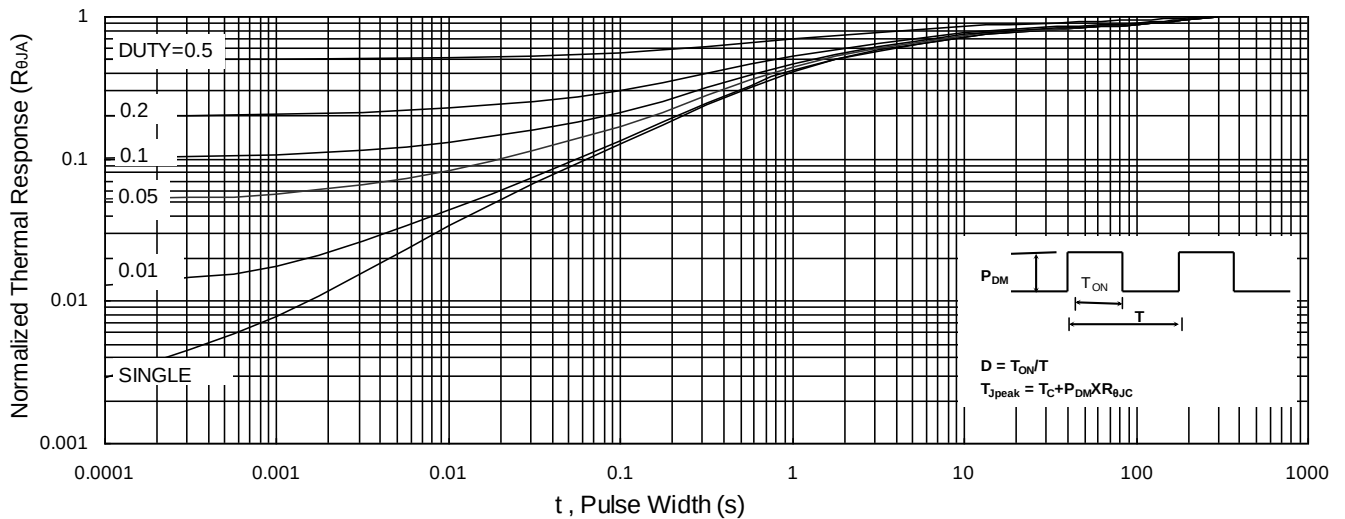


Fig.9 Normalized Maximum Transient Thermal Impedance

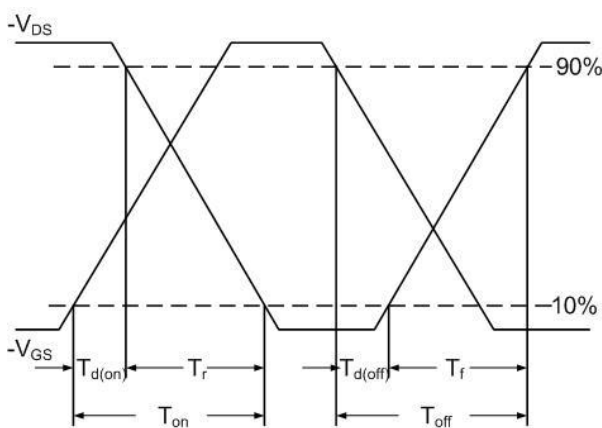


Fig.10 Switching Time Waveform

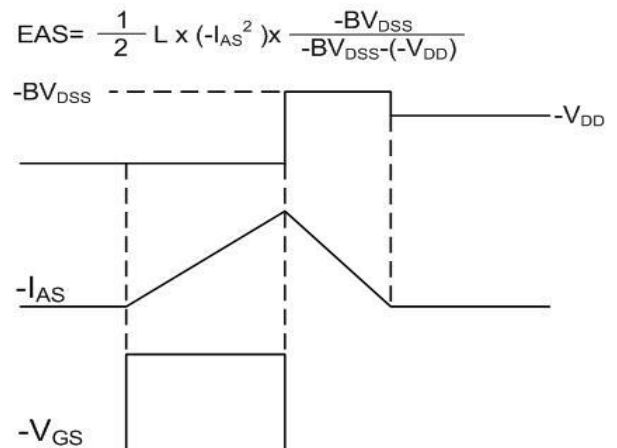


Fig.11 Unclamped Inductive Waveform